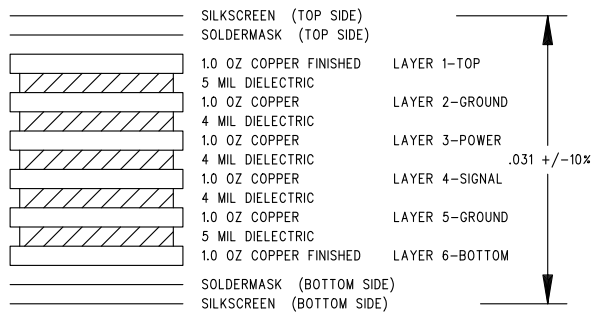


LAYUP DETAIL  
6 LAYER

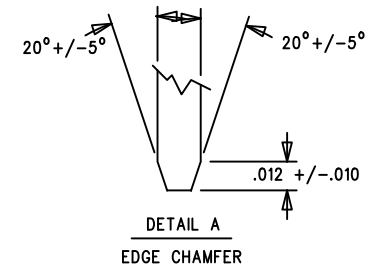
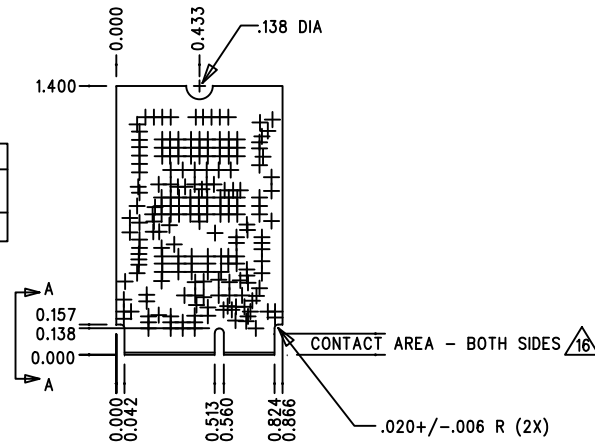
SIZE	QTY	SYM	PLATED	TOL
0.01	203	+	YES	+/-0.003

## REVISION HISTORY

C2	Initial Release	11/30/2017
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## IMPEDANCE CONTROLLED SIGNALS

Signal & Pairs	Trace Width	Impedance Requirement	Signal Layers	Reference Layer
USB+ USB-	7.1 MIL TRACE 7.9 MIL GAP	90 Ohm +/-10% differential	Layers 1&6	Layers 2&5
All others	6 MIL	50 Ohm +/-10% single-ended	Layers 1,4&6	Layers 2&5; no ref where void



## Notes: apply unless specified otherwise.

- Material: Polyclad PCL-FR-370HR or equivalent. Overall thickness = .031" +/-10%
- Unless otherwise specified, all hole dimensions apply after plating.  
All plated through holes to have a minimum of .001" copper.
- All holes shall be located within .003" diameter of true position. Layer to layer registration shall be within .003". All holes surrounded by land shall have a minimum annular ring of .001". All via in pads must be filled with THP-100DX1 material.
- Apply soldermask over bare copper, color GREEN; mask shall meet IPC-SM-840 to a thickness specification of 5 um to 18 um.
- All exposed copper shall be coated with electroless nickel/immersion gold finish. Nickel plating shall be 118-275u" thick over copper. Gold plating shall be 2-8u" thick over nickel. Boards shall pass solderability testing per J-STD-003. There shall be no evidence of exposed copper.
- Warp or twist of board shall not exceed .010 inch per inch.
- Silkscreen using non-conductive epoxy ink. Color: WHITE.
- Remove all burrs and break all sharp edges.
- Board shall meet the requirements of UL796 with a flammability rating of 94V-0.  
Vendor's UL logo or designation shall be located on the solder side of board.
- Fabricate in accordance with ANSI/IPC-A-600, class 2.
- Dimensions and tolerances per ASME Y14.5M.
- Fabricate using artwork 330-334-GBR Rev C2.
- Any rework shall be to IPC-R-700C guidelines and tested per section VI. Test results shall be included with each shipment. Reworked items shall be separated from non-reworked items and the outer packaging labeled as "reworked items enclosed".
- Tent all vias both sides.
- All materials and processes must be RoHS compliant.

16. Plating requirement for Gold Fingers: 30u Gold over 100-200u Nickel.

Lantronix

TITLE:

FABRICATION DRAWING  
XPICO 240 Connector Module

DWG A	DWG NO: 330-334-FAB-R	REV: C2
SIZE	SCALE: 1 : 1	SHEET: 1 OF 1